

18-Line SCSI Terminator (Reverse Disconnect)

FEATURES

- Complies with SCSI, SCSI-2, SCSI-3 and FAST-20 Standards
- 2pF Channel Capacitance During Disconnect
- 50 μ A Supply Current in Disconnect Mode
- 110 Ω Termination
- SCSI Hot Plugging Compliant, 10nA Typical
- +400mA Sinking Current for Active Negation
- -650mA Sourcing Current for Termination
- Trimmed Impedance to 5%

DESCRIPTION

The UCC5617 provides 18 lines of active termination for a SCSI (Small Computers Systems Interface) parallel bus. The SCSI standard recommends and Fast-20 (Ultra) requires active termination at both ends of the cable.

Pin for pin compatible with the UC5609, the UCC5617 is ideal for high performance 5V SCSI systems, T_{mpwr} 4.0V to 5.25V. During disconnect the supply current is only 50 μ A typical, which makes the IC attractive for lower powered systems.

The UCC5617 is designed with a low channel capacitance of 2pF, which eliminates effects on signal integrity from disconnected terminators at interim points on the bus.

The power amplifier output stage allows the UCC5617 to source full termination current and sink active negation current when all termination lines are actively negated.

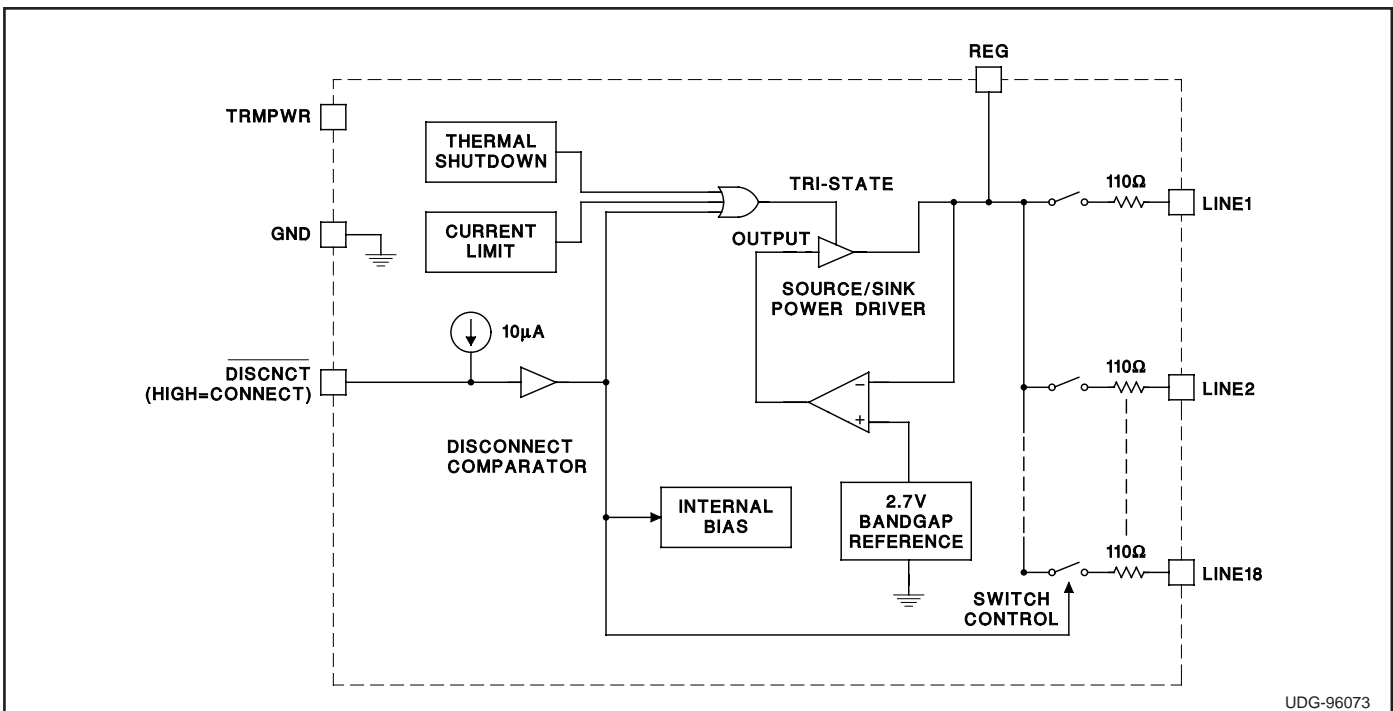
The UCC5617, as with all Unitrode terminators, is completely hot pluggable and appears as high impedance at the terminating channels with $TRMPWR=0V$ or open.

Internal circuit trimming is utilized, first to trim the 110 Ω impedance, and then most importantly, to trim the output current as close to the maximum SCSI-3 specification as possible, which maximizes noise margin in fast SCSI operation.

Other features include thermal shutdown and current limit.

This device is offered in low thermal resistance versions of the industry standard 28 pin wide body SOIC, TSSOP and PLCC.

BLOCK DIAGRAM



UDG-96073

Circuit Design Patented

ELECTRICAL CHARACTERISTICS Unless otherwise stated these specifications apply for $T_A = 0^\circ\text{C}$ to 70°C ,
 $\text{TRMPWR} = 4.75\text{V}$, $\text{DISCNCT} = 4.75\text{V}$, $T_A = T_J$.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Supply Current Section					
Termprwr Supply Current	All termination lines = Open		1	2	mA
	All termination lines = 0.2V		420	450	mA
Power Down Mode	$\text{DISCNCT} = 0\text{V}$		50	100	μA
Output Section (Termination Lines)					
Termination Impedance	(Note 3)	104.5	110	115.5	Ω
Output High Voltage	$V_{\text{TRMPWR}} = 4\text{V}$ (Note 1)	2.6	2.8	3	V
Maximum Output Current	$V_{\text{LINE}} = 0.2\text{V}$, $T_J = 25^\circ\text{C}$	-22.1	-23.3	-24	mA
	$V_{\text{LINE}} = 0.2\text{V}$	-20.7	-23.3	-24	mA
	$V_{\text{LINE}} = 0.2\text{V}$, $\text{TRMPWR} = 4\text{V}$, $T_J = 25^\circ\text{C}$ (Note 1)	-21	-23	-24	mA
	$V_{\text{LINE}} = 0.2\text{V}$, $\text{TRMPWR} = 4\text{V}$ (Note 1)	-20	-23	-24	mA
	$V_{\text{LINE}} = 0.5\text{V}$			-22.4	mA
Output Leakage	$\text{DISCNCT} = 0\text{V}$, $\text{TRMPWR} = 0\text{V}$ to 5.25V , $\text{REG} = 0.2\text{V}$, $V_{\text{LINE}} = 5.25\text{V}$		10	400	nA
Output Capacitance	$\text{DISCNCT} = 2.4\text{V}$ (Note 2)		2	3.5	pF
Regulator Section					
Regulator Output Voltage		2.6	2.8	3	V
Drop Out Voltage	All Termination Lines = 0.2V		0.4	0.8	V
Short Circuit Current	$V_{\text{REG}} = 0\text{V}$	-475	-650	-850	mA
Sinking Current Capability	$V_{\text{REG}} = 3.5\text{V}$	200	400	800	mA
Thermal Shutdown			170		$^\circ\text{C}$
Thermal Shutdown Hysteresis			10		$^\circ\text{C}$
Disconnect Section					
Disconnect Threshold		0.8	1.5	2	V
Input Current	$\text{DISCNCT} = 0\text{V}$		-10	-30	μA

Note 1: Measuring each termination line while other 17 are low (0.2V).

Note 2: Guaranteed by design. Not 100% tested in production.

Note 3: Tested by measuring I_{OUT} with $V_{\text{OUT}} = 0.2\text{V}$ and V_{OUT} with no load, then calculating:

$$Z = \frac{V_{\text{OUT N.L.}} - 0.2\text{V}}{I_{\text{OUT at } 0.2\text{V}}}$$

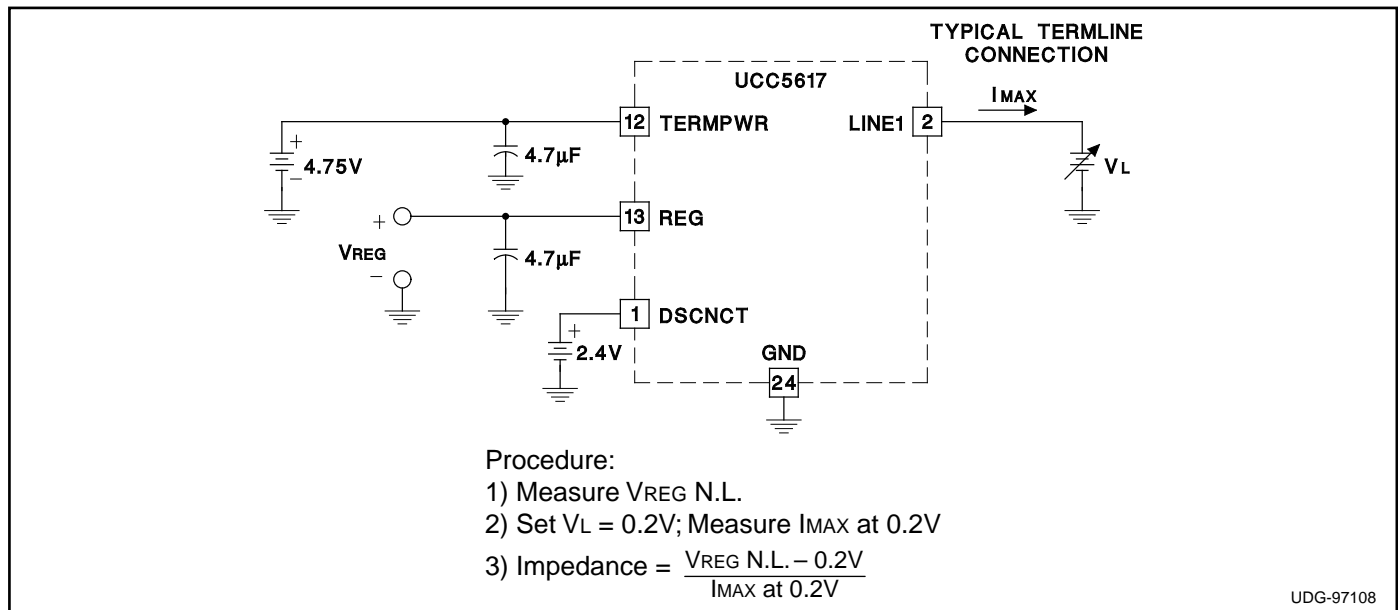


Figure 1. Termline Impedance Measurement Circuit

PIN DESCRIPTIONS

DISCNCT: Taking this pin low causes the 18 channels to become high impedance and the chip to go into low-power mode; a high or open state allows the channels to provide normal termination.

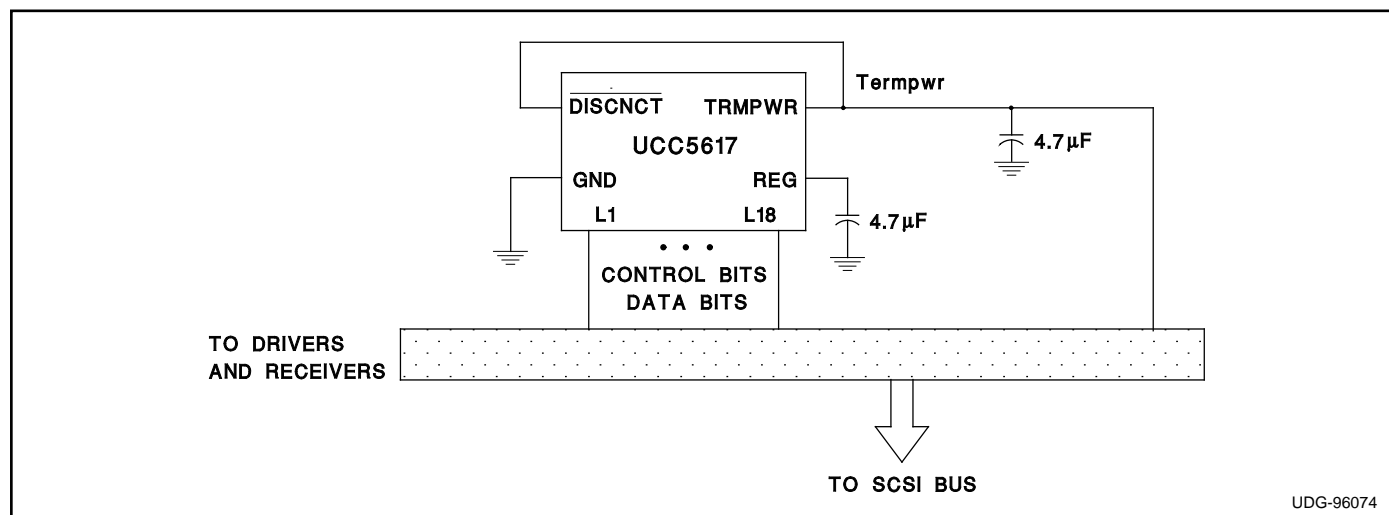
GND: Ground reference for the IC.

LINE 1-18: 110Ω termination channels.

REG: Output of the internal 2.8V regulator.

TRMPWR: Power for the IC.

APPLICATION INFORMATION



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